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Abstract of the Disclosure

Al A resist pattern forming apparatus having a controller having a controlling portion that controls processing of a coating and developing apparatus with coating unit and developing units provided therewith and an aligner being connected thereto, while an inspecting portion measures at least one of a plurality of measurement items selected from, reflection ratio and film thickness of a base film and a resist film, line width after the development, an accuracy that the base film matches with a resist pattern, a defect after the development, and so on. The measured data is transmitted to the controller, and a parameter subject to amendment is selected based on the corresponding data of each of the measurement item such as the film thickness of the resist and the line width after the development, and the amendment of the parameters subject to the amendment is performed. This results in a reduced workload of an operator, and the appropriate amendment can be performed.

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